SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION:	PLANT LOCATION:	CAGE Code: 6T499
FTG Circuits Fredericksburg Inc. 1026 Warrenton Road, Fredericksburg, VA, 22406-6200 US	Same Address as Manufacturer	Phone: 540-753-5511, x177 Fax: 540-752-2109 EMail: quality@colonialcircuits.com

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
Qualification Letters: VQE-04-6002
Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
Max. Panel Size: 18" x 24"
Max. Number of Layers: 14
Max. Board Thickness: .088"
Min. Hole Size: .021" Drilled Plated-Through Hole Before Plating
Aspect Ratio: 4.2:1 Through-Hole
Min. Conductor Width/Space: .006"/.005"
Hole Preparation: Plasma Desmear, Plasma Etchback
Hole Wall Conductive Coating: Carbon-based
Copper Plating: Direct Current Plate
Solder Resist: Liquid Photoimageable
Finish System: ENIG, HASL

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
Qualification Letters: VQE-04-6002, VQE-20-034719
Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
Max. Panel Size: 18" x 24"
Max. Number of Layers: 16
Max. Board Thickness: .127"
Min. Hole Size: .015"
Aspect Ratio: 8.5:1 Through-Hole
Min. Conductor Width/Space: .005"/.004"
Hole Preparation: Plasma Desmear, Plasma Etchback
Hole Wall Conductive Coating: Carbon-based
Copper Plating: Direct Current Plate
Solder Resist: Liquid Photoimageable
Finish System: ENIG, HASL

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
Qualification Letters: VQE-04-6002
Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
Flex Base Material: Copper Clad Polyimide with Acrylic Adhesive
Max. Panel Size: 12" x 18"
Max. Number of Layers: 10
Max. Board Thickness: .093"
Min. Hole Size: .025" Drilled Plated-Through Hole Before Plating
Aspect Ratio: 3.7:1 Through-Hole
Min. Conductor Width/Space: .005"/.005"
Hole Preparation: Plasma Desmear, Plasma Etchback
Hole Wall Conductive Coating: Carbon-based
Copper Plating: Direct Current Plate
Solder Resist: Liquid Photoimageable
Finish System: ENIG, HASL
Flex Usage: Use A (Flex During Installation),

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